# PRODUCT CHANGE NOTICE

<table>
<thead>
<tr>
<th>PART NUMBER(S):</th>
<th>PCN No.: 06-0130-02</th>
</tr>
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<tbody>
<tr>
<td>Please see attachment.</td>
<td>DATE: January 30, 2006</td>
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</tbody>
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## PART DESCRIPTION:
Power Management and Interface Products – Change in Wafer Fabrication Site

## LEVEL OF CHANGE:
- [X] Level I, Customer Approval.
- [ ] Level II, Customer Information.

## PRODUCT ATTRIBUTE AFFECTED:
- [ ] Material Change
- [ ] Design Change
- [X] Process Change
- [ ] Data Sheet Change
- [ ] Package Change
- [ ] Packing / Shipping
- [X] Other, Explain: Wafer Fabrication Site Transfer

## DESCRIPTION OF CHANGE:
Announcing transfer of certain Power Management and Interface Products from Hillview wafer fabrication facility to wafer foundry SILAN. See attached Product List no. 02.

## REASON FOR CHANGE:
Power Management and Interface products as listed are being transferred to external wafer foundry, due to cessation of operations of the Sipex Hillview Wafer Fabrication manufacturing site.

## FABRICATION PROCESS QUALIFICATION COMPLETED (DATE): May 28, 2006

## PRODUCT CHARACTERIZATION COMPLETED: June 18, 2006

## SAMPLES* AVAILABLE (DATE): June 11, 2006

* Samples representative of product from the Product Family being transferred.
PRODUCT CHANGE NOTICE

EARLIEST DATE OF PRODUCTION
SHIPMENTS: October 16, 2006

EFFECTIVITY CHANGE DATE OR DATE CODE: Work week associated with earliest production shipment.

[ ] STANDARD DISTRIBUTION [X] CUSTOM DISTRIBUTION

PERSON TO CONTACT WITH QUESTIONS:

Fred Claussen
VP Quality Assurance and Reliability
Sipex Corporation
Phone Number: 408-935-7644
FAX NUMBER: 408-935-7678
PCN No.: 06-0130-02

List 2

SP508CF
SP508CF-L
SP508EF
SP508EF-L
SP509CF
SP509CF-L
SP508CF
SP508CF-L
SP508EF
SP508EF-L
SP509CF
SP509CF-L
SP508CF
SP508CF-L
SP508EF
SP508EF-L
SP509CF
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